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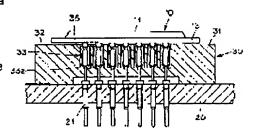
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## (54) SOCKET FOR MEASURING BALL GRID ARRAY SEMICONDUCTOR

## (57)Abstract:

PURPOSE: To improve contact reliability by punching a specific sheet metal having a spring function to a tuning fork shape for use as a contact pin having two-point contact with a solder ball.

CONSTITUTION: A branch contact pin 36 is formed out of a sheet metal having a spring function such as beryllium bronze and phosphor bronze punched into a tuning fork shape. Also, the end of an elastic branch section has the housing 31 of a BGA package measurement socket 30 made socket by machining a plate material, where in contact with the solder ball of a BGA package 10. In addition, receiving holes reaching from the upper surface of a housing 31 to the lower surface thereof are drilled and arrayed, so as to correspond to balls 12 arranged and positioned in a matrix on the lower surface of the package 10 laid on the surface 32. According to this construction, the branch contact pins 30 of the socket 30 for measuring a ball grid array BGA semiconductor comes to have the elastic branch section in two-point contact with the solder balls, thereby improving contact reliability.



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